



Pin Description

Pin #	Pin Name	Type	Pin Description
1	MOS_D	MOSFET	Drain of MOSFET
2	MOS_D	MOSFET	Drain of MOSFET
3	ON_MOS	Input	Turns on MOS (4 M Ω pull down resistor). Tied to Pin 5 on PCB.
4	VDD	VDD	+5VDD Power
5	ON_MOS	Input	Turns on MOS (4 M Ω pull down resistor). Tied to Pin 3 on PCB.
6	MOS_D	MOSFET	Drain of MOSFET
7	MOS_D	MOSFET	Drain of MOSFET
8	MOS_S	MOSFET	Source of MOSFET
9	MOS_S	MOSFET	Source of MOSFET
10	CAP_MOS	Input	Sets ramp and turn on time for MOSFET. Tied to Pin 12 on PCB.
11	GND	GND	Ground
12	CAP_MOS	Input	Sets ramp and turn on time for MOSFET. Tied to Pin 10 on PCB.
13	MOS_S	MOSFET	Source of MOSFET
14	MOS_S	MOSFET	Source of MOSFET

Ordering Information

Part Number	Type	Production Flow
SLG59M1568V	STDFN 14L	Industrial, -40 °C to 85 °C
SLG59M1568VTR	STDFN 14L (Tape and Reel)	Industrial, -40 °C to 85 °C



Absolute Maximum Ratings

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
V_D	Power Supply		--	--	6	V
T_S	Storage Temperature		-65	--	150	°C
ESD_{HBM}	ESD Protection	Human Body Model	2000	--	--	V
W_{DIS}	Package Power Dissipation		--	--	1.2	W
IDS_{MAX}	Max Operating Current				9	A
MOSFET IDS_{PK}	Peak Current from Drain to Source	For no more than 10 continuous seconds out of every 100 seconds	--	--	12	A

Note: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

$T_A = -40\text{ °C}$ to 85 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Power Supply Voltage		2.5	--	5.5	V
I_{DD}	Power Supply Current when OFF		--	0.1	1	μA
	Power Supply Current ON_MOS_1 & ON_MOS_2 (Steady State)		--	50	75	μA
RDS_{ON}	ON Resistance	$T_A\ 25\text{ °C}$ MOSFET @100 mA	--	7.3	9	mΩ
		$T_A\ 70\text{ °C}$ MOSFET @100 mA	--	8	11	mΩ
		$T_A\ 85\text{ °C}$ MOSFET @100 mA		8.5	11.5	mΩ
MOSFET IDS	Current from Drain to Source for each MOSFET	Continuous	--	--	9	A
V_D	Drain Voltage		1.0	5.0	V_{DD}	V
T_{ON_Delay}	ON pin Delay Time	50% ON to Ramp Begin	0	300	500	μs
T_{Total_ON}	Total Turn On Time	50% ON to 90% V_S	Configurable ¹			ms
		Example: CAP (Pin 10 & 12) share a single 4nF capacitor, $V_{DD} = V_D = 5\text{ V}$, Source_Cap = 10 μF, $R_L = 20\ \Omega$	--	1.1	--	ms
$T_{SLEWRATE}$	Slew Rate	10% V_S to 90% V_S	Configurable ¹			V/ms
		Example: CAP (Pin 10 & 12) share a single 4nF capacitor, $V_{DD} = V_D = 5\text{ V}$, Source_Cap = 10 μF, $R_L = 20\ \Omega$	--	6.0	--	V/ms
CAP_{SOURCE}	Source Cap	Source to GND	--	--	1000	μF
R_{DIS}	Discharge Resistance		100	210	300	Ω
ON_ V_{IH}	High Input Voltage on ON pin		0.85	--	V_{DD}	V
ON_ V_{IL}	Low Input Voltage on ON pin		-0.3	0	0.3	V
I_{LIMIT}	Active Current Limit	MOSFET will automatically limit current when $V_S > 250\text{ mV}$	--	12.0	--	A
	Short Circuit Current Limit	MOSFET will automatically limit current when $V_S < 250\text{ mV}$	--	0.5	--	A
$THERM_{ON}$	Thermal shutoff turn-on temperature		--	125	--	°C
$THERM_{OFF}$	Thermal shutoff turn-off temperature		--	100	--	°C



$T_A = -40\text{ }^{\circ}\text{C}$ to $85\text{ }^{\circ}\text{C}$ (unless otherwise stated)

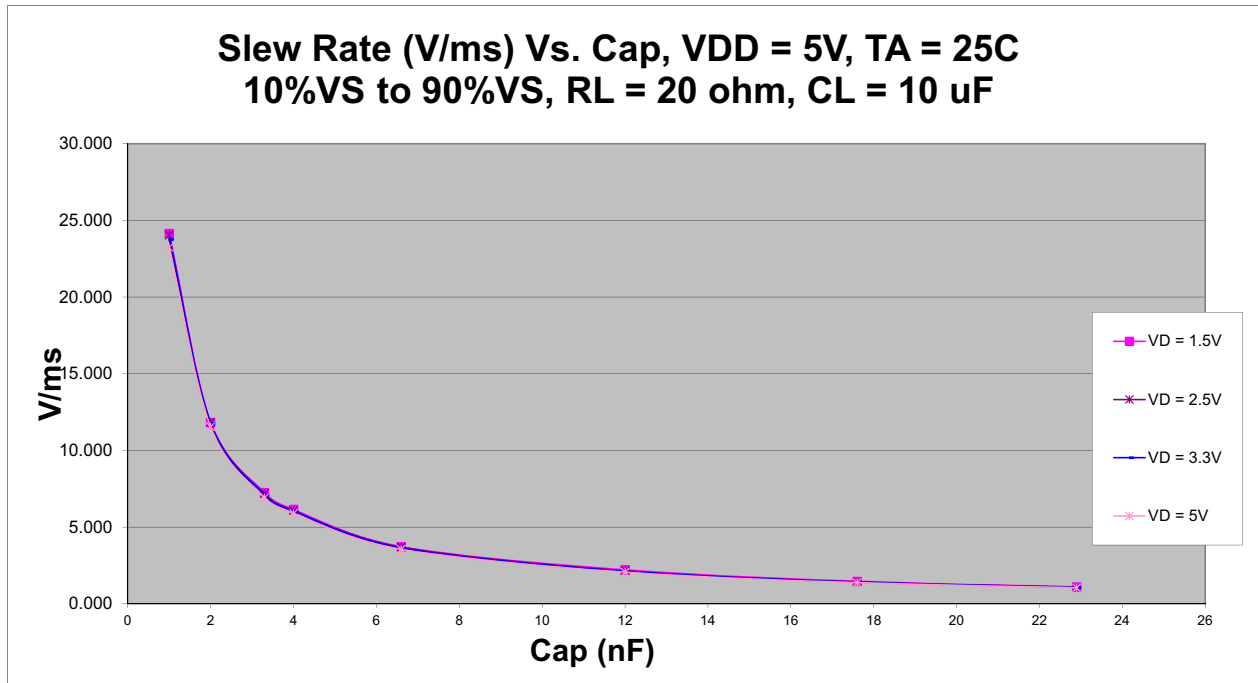
Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
THERM _{TIME}	Thermal shutoff time		--	--	1	ms
T _{OFF_Delay}	OFF Delay Time	50% ON to V _S Fall, V _{DD} = V _D = 5 V	--	--	15	μs

Notes:

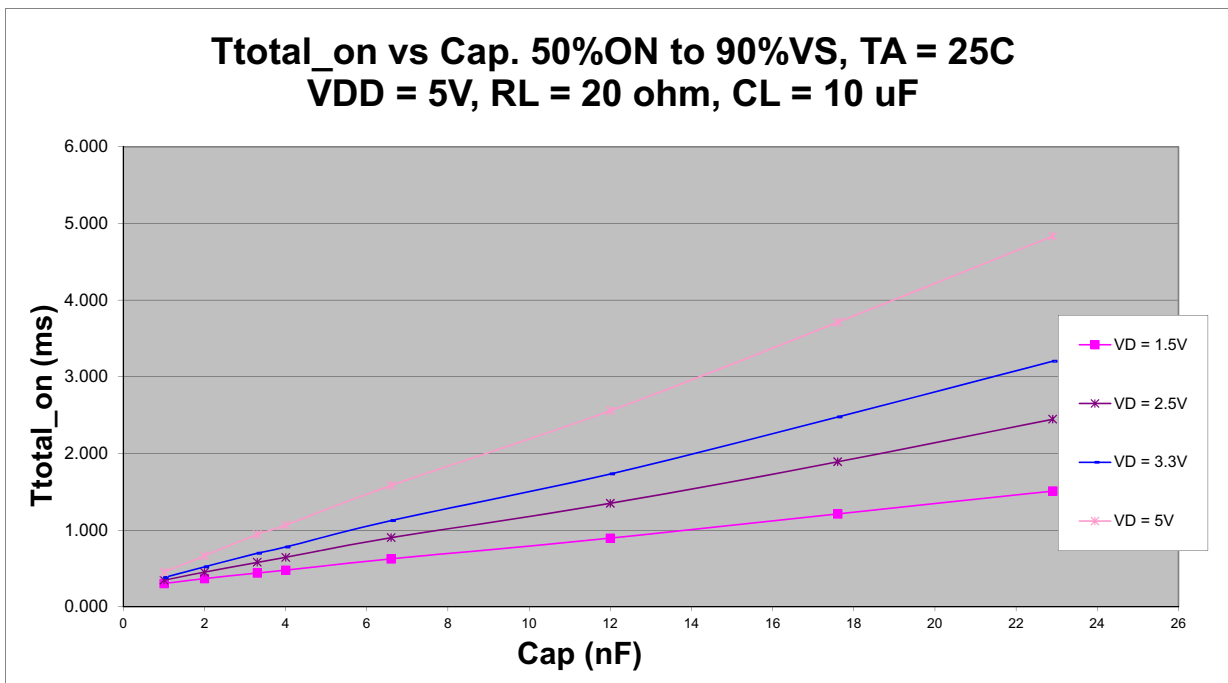
1. Refer to table for configuration details.



T_{SLEW} vs. CAP

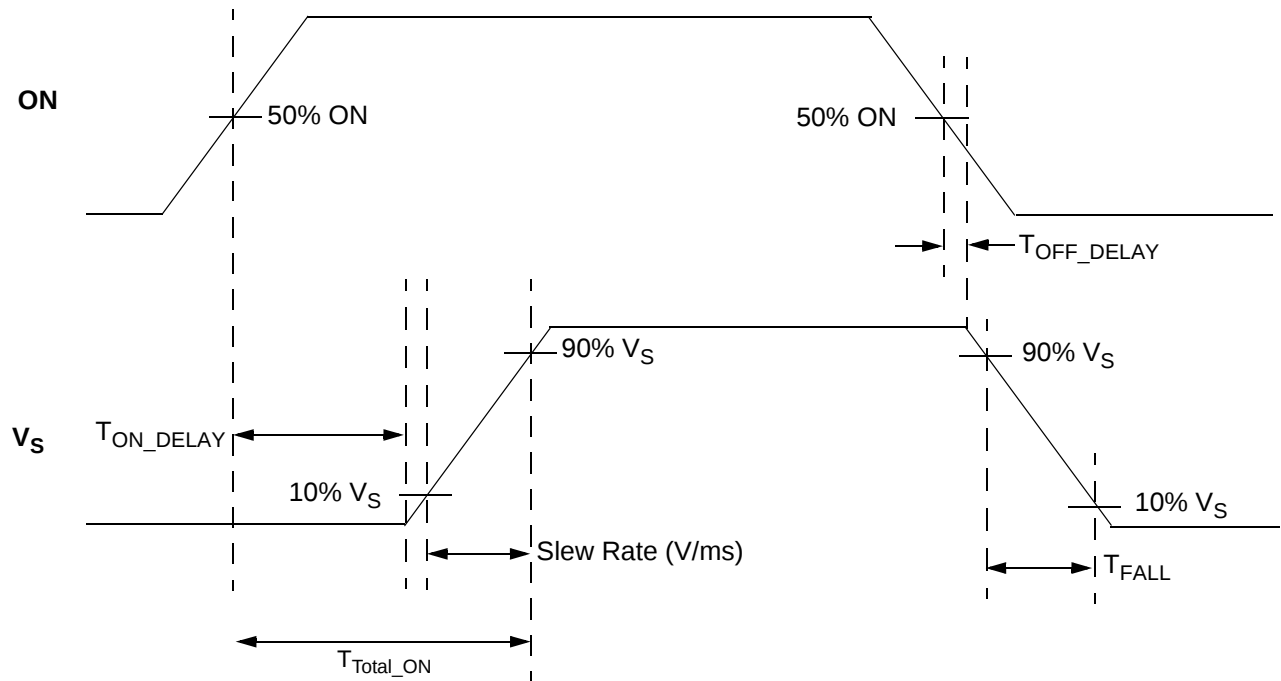


T_{TOTAL_ON} vs. CAP





T_{Total_ON} , T_{ON_Delay} and Slew Rate Measurement





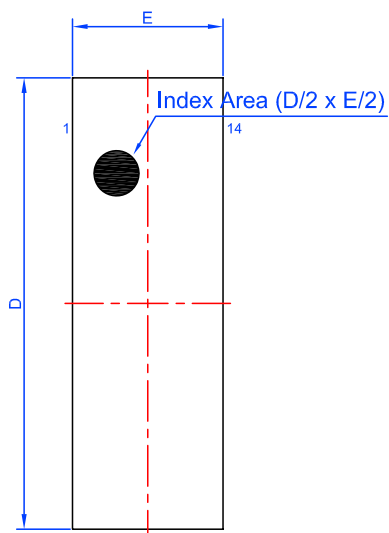
Package Top Marking System Definition



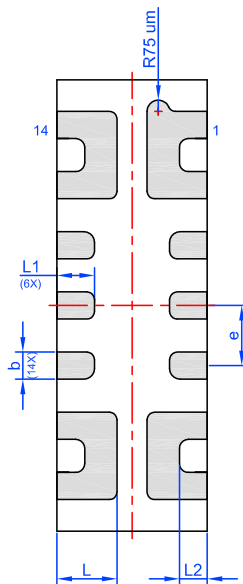


Package Drawing and Dimensions

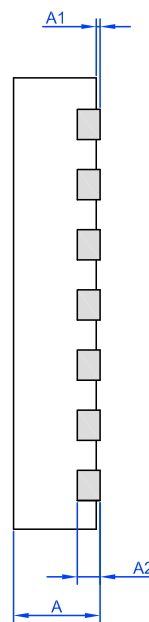
14 Lead STDFN Package 1 mm x 3 mm (Fused Lead)



Top View



BTM View



SIDE View

Unit: mm

Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	2.95	3.00	3.05
A1	0.005	-	0.050	E	0.95	1.00	1.05
A2	0.10	0.15	0.20	L	0.35	0.40	0.45
b	0.13	0.18	0.23	L1	0.20	0.25	0.30
e	0.40 BSC			L2	0.06	0.11	0.16

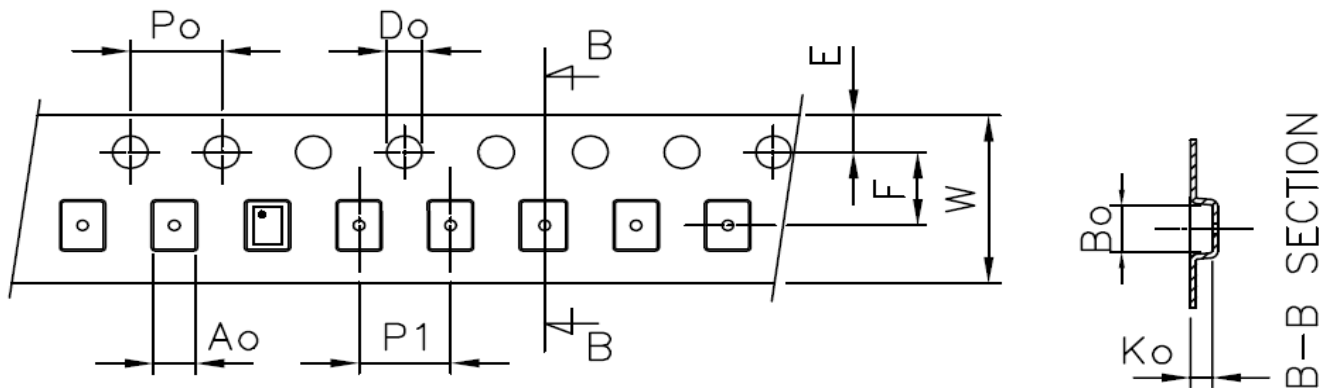


Tape and Reel Specifications

Package Type	# of Pins	Nominal Package Size	Units per Reel	Max Units per Box	Reel & Hub Size (mm)	Trailer A		Leader B		Pocket Tape (mm)	
						Pockets	Length (mm)	Pockets	Length (mm)	Width	Pitch
STDFN 14L 1x3mm 0.4P FC	14	1x3x0.55mm	3000	3000	178/60	100	400	100	400	8	4

Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length [mm]	Pocket BTM Width [mm]	Pocket Depth [mm]	Index Hole Pitch [mm]	Pocket Pitch [mm]	Index Hole Diameter [mm]	Index Hole to Tape Edge [mm]	Index Hole to Pocket Center [mm]	Tape Width [mm]
	A0	B0	K0	P0	P1	D0	E	F	W
STDFN 14L 1x3mm 0.4P FC	1.15	3.15	0.7	4	4	1.5	1.75	3.5	8

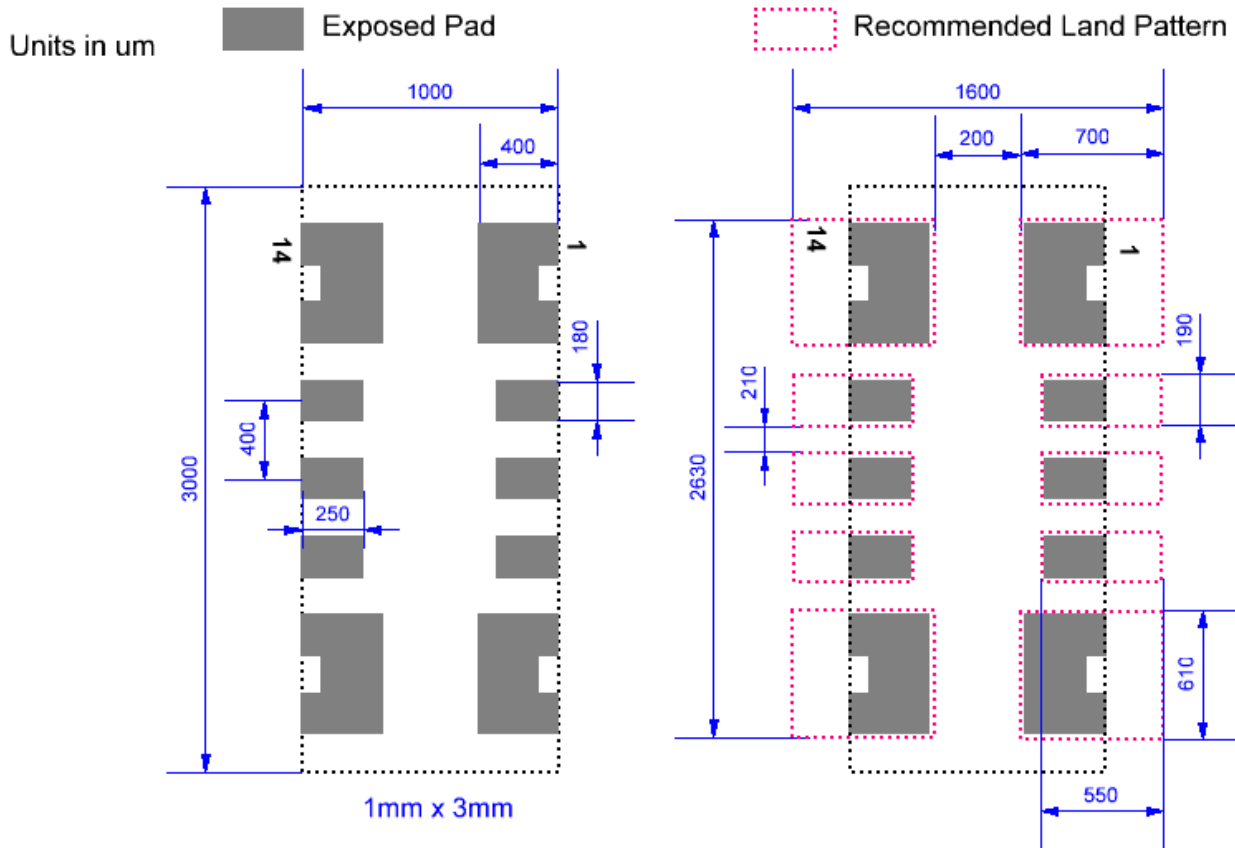


Recommended Reflow Soldering Profile

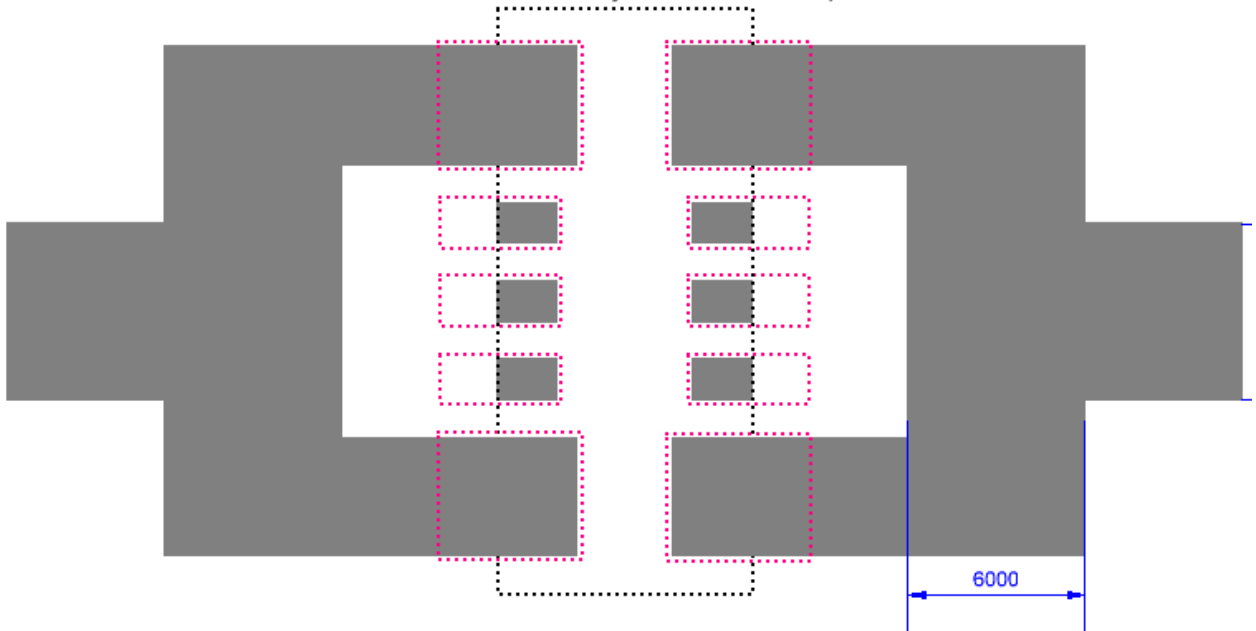
Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 1.65 mm³ (nominal). More information can be found at www.jedec.org.



Recommended Land Pattern and PCB Layout



Recommended PCB Layout for external power traces





Revision History

Date	Version	Change
3/15/2016	1.04	Fixed RDSon values